



Device Material Content

5555 NE Moore Ct. Hillsboro OR 97124 custreg@latticesemi.com					Package Code: FTN256 (v.1)		Assembly: ASEM Size (mm): 17 x 17	
Package: 256 ftBGA Total Device Weight 0.705 Grams					Products: LA-XP2, LAMXO		Lead pitch (mm): 1 MSL: 3 Reflow max (°C): 260	
June, 2022	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	1.00%	0.0071			Silicon chip	7440-21-3	100.00%	Die size: 3.35 x 3.35 mm
Mold Compound	55.31%	0.390	2.77% 2.77% 0.11% 48.56% 1.11%	0.0195 0.0195 0.0008 0.3424 0.0078	Epoxy Resin Phenol Resin Carbon Black Silica Others	- - 1333-86-4 60676-86-0 -	5.00% 5.00% 0.20% 87.80% 2.00%	Mold Compound: Hitachi CEL9750ZHF10AKL-U (ULA)
D/A Epoxy	0.16%	0.0011	0.13% 0.03%	0.00088 0.00022	Silver (Ag) Organic esters and resins	7440-22-4 -	80.00% 20.00%	Die attach epoxy: Henkel (Ablebond) 2100A
Wire	1.07%	0.0075	1.07%	0.0075	Gold (Au)	7440-57-5	100.00%	0.8 to 1.0 mil diameter; 1 wire per package lead
Solder Balls	13.78%	0.097	13.30% 0.41% 0.07%	0.0937 0.0029 0.0005	Tin (Sn) Silver (Ag) Copper (Cu)	7440-31-5 7440-22-4 7440-50-8	96.50% 3.00% 0.50%	SAC305
Substrate	13.11%	0.0924	4.20% 8.91%	0.0296 0.0628	BT Resins Glass fiber	- 65997-17-3	32.00% 68.00%	BT Resin CCL-HL832NX-A
Foil	9.56%	0.0674	8.14% 1.87% 0.07%	0.0574 0.0096 0.0004	Copper Nickel Gold	7440-50-8 7440-02-0 7440-57-5	85.15% 14.28% 0.57%	
Solder Mask	6.01%	0.0424	3.38% 0.96% 1.32% 0.18% 0.17%	0.02381 0.00678 0.00932 0.00127 0.00119	Quartz 3-methoxy-3-methylbutylacetate Barium Sulfate Talc (containing no asbestiform fibers) Trade secret ingredients	14808-60-7 103429-90-9 7727-43-7 14807-96-6 -	56.20% 16.00% 22.00% 3.00% 2.80%	Solder mask PSR4000 AUS 308

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